

-40V P-Channel Enhancement Mode MOSFET

Description

The AP20P04D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -40V I_{D} = -20A$

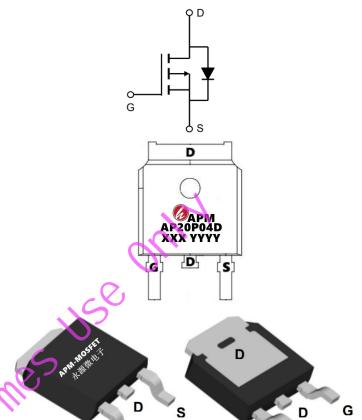
 $R_{DS(ON)} < 40 \text{m}\Omega$ @ V_{GS} =-10V (Type: 30m Ω)

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP20P04D	TO-252-3L	AP20P04D XXX YYYY	2500

Absolute Maximum Ratings (T_c=25 ℃ unless otherwise noted)

Symbol	Parameter	rameter Rating	
VDS /	Drain-Source Voltage		V
VGS	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, -V _{GS} @ -10V ¹	-20	А
I _D @T _C =100°C	Continuous Drain Current, -V _{GS} @ -10V ¹	-18	Α
IDM	IDM Pulsed Drain Current ²		А
EAS	S Single Pulse Avalanche Energy ³		mJ
IAS	Avalanche Current	-27.2	А
P _D @T _C =25°C	Total Power Dissipation ⁴	otal Power Dissipation ⁴ 31.3	
TSTG	Storage Temperature Range -55 to 150		℃
TJ	Operating Junction Temperature Range -55 to 150		°C
R _θ JA	Thermal Resistance Junction-Ambient ¹	62	°C/W
R _θ JC	Thermal Resistance Junction-Case ¹	4	°C/W



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Electrical Characteristics (T_J=25°C, unless otherwise noted)

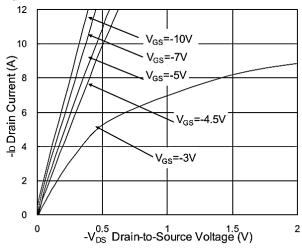
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-40	-46		V	
△BVɒss/△Tɹ	BV _{DSS} Temperature Coefficient	Reference to 25℃, I _D =-1mA		-0.012		V/℃	
	Static Proin Source On Bosistanas ²	V _{GS} =-10V , I _D =-18A		30	40	0	
Rds(on)	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V , I _D =-12A		45	60	mΩ	
V _{GS} (th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.6	-2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS , ID250UA		4.32		mV/℃	
Ipss	Drain-Source Leakage Current	V _{DS} =-32V , V _{GS} =0V , T _J =25℃			1	^	
IDSS	Diain-Source Leakage Current	V _{DS} =-32V , V _{GS} =0V , T _J =55℃	l.		5	uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-18A		12.6		S	
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		13		Ω	
Qg	Total Gate Charge (-4.5V)	Q ₁		9		nC	
Qgs	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-4.5V , I _D =-		2.54			
Qgd	Gate-Drain Charge			3.1			
Td(on)	Turn-On Delay Time	6		19.2			
Tr	Rise Time	V_{DD} =-15V, V_{GS} =-10V , R_{G} =3.3Ω,		12.8		no	
Td(off)	Turn-Off Delay Time	I _D =-1A		48.6		- ns	
T _f	Fall Time			4.6			
Ciss	Input Capacitance			1004			
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		108		pF	
Crss	Reverse Transfer Capacitance			80			
ls	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current			-23	Α	
lsм	Pulsed Source Current ^{2,5}	3 12 21,7 2.22 23			-46	Α	
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1	V	

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V DD =-25V,V GS =-10V,L=0.1mH,I AS =-27.2A
- 4. The power dissipation is limited by 150 $^{\circ}\mathrm{C}$ junction temperature
- 5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.

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Typical Characteristics



60 55 C(50) S(345) 40 35 30 2 4 -V_{GS}(V) 8 10

Fig.1 Typical Output Characteristics

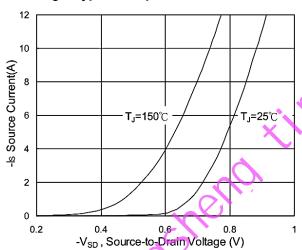


Fig.2 On-Resistance v.s Gate-Source

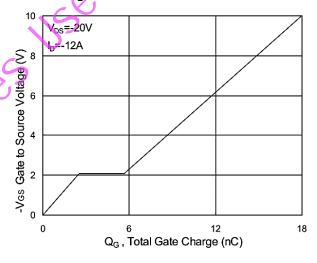


Fig.3 Forward Characteristics of Reverse

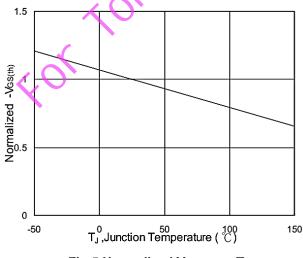


Fig.4 Gate-Charge Characteristics

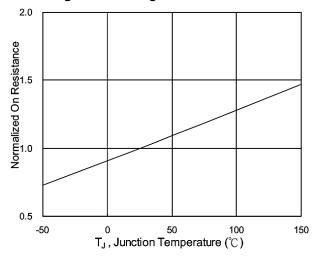


Fig.5 Normalized V_{GS(th)} v.s T_J Fig.6 Normalized R_{DSON} v.s T_J



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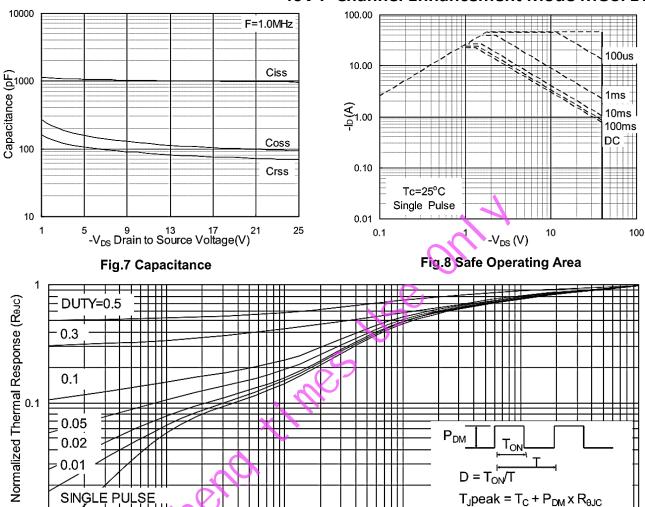
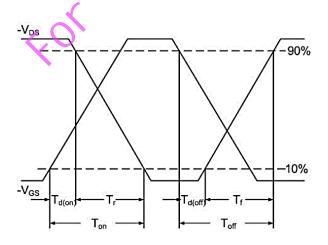


Fig.9 Normalized Maximum Transient Thermal Impedance

t, Pulse Width (s)

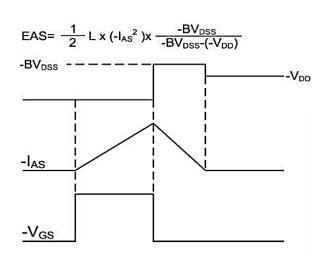
0.01

0.001



0.0001

Fig.10 Switching Time Waveform



0.1

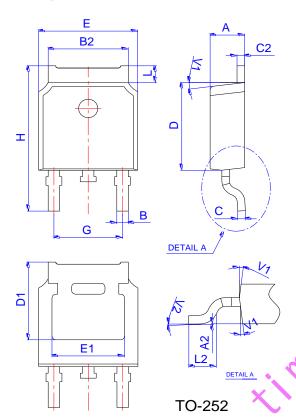
Fig.11 Unclamped Inductive Waveform

0.00001



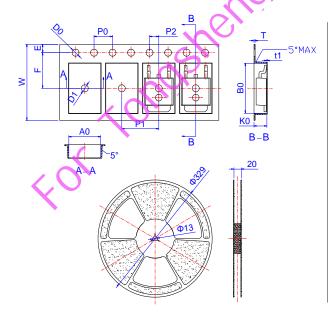
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Package Mechanical Data:TO-252-3L



	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202		0.216	
С	0.40		0.60	0.016		0.024	
C2	0.44		0.58	0.017		0.023	
D	5.90		6.30	0.232		0.248	
D1		5.30REF			0.209REF		
Е	6.40		6.80	0.252		0.268	
E1	4.63			0.182			
G	4.47	()	4.67	0.176		0.184	
Н	9.50		10.70	0.374		0.421	
L	1.09		1.21	0.043		0.048	
L2	1.35		1.65	0.053		0.065	
V1		7°			7°		
V2	0°		6°	0°		6°	
•							

Reel Spectification-TO-252



	Dimensions					
Ref. N		Millimeters		Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
В0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
Т	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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Edition	Date	Change
Rve1.0	2021/1/10	Initial release

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